

Special Issue

Intelligent Computing and Remote Sensing—2nd Edition

Message from the Guest Editors

The previous Special Issue showcased the fusion of intelligent computing and remote sensing, addressing key challenges in the field. Building on its success, we are excited to announce the 2nd Edition. This upcoming Special Issue aims to continue exploring the applications of intelligent computing in remote sensing, welcoming submissions on image processing, on-board information processing, big data analysis, and UAV systems. We invite theoretical research, practical applications, reviews, and surveys. This is a platform for cutting-edge research and advancements in intelligent computing and remote sensing. Join scholars and experts globally to drive innovation in this field. Contribute to this Special Issue, shaping the future of intelligent computing in remote sensing.

Guest Editors

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Dr. Feng Gao

Deadline for manuscript submissions

closed (30 December 2025)



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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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